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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/675,258	09/30/2003	Seung H. Kang	AYUKAWA 1-4-1-162-30	4017
47396	7590	10/13/2006	EXAMINER LE, THAO X	
HITT GAINES, PC AGERE SYSTEMS INC. PO BOX 832570 RICHARDSON, TX 75083			ART UNIT 2814	PAPER NUMBER

DATE MAILED: 10/13/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

10/675,258

Applicant(s)

KANG ET AL.

Examiner

Thao X. Le

Art Unit

2814

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 13 September 2006.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-6 and 8-28 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-6, 8-16 and 26-28 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 13 Sept. 2006 has been entered.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

3. Claims 1-4, 6, 8-10, 12-16, and 26 are rejected under 35 U.S.C. 102(e) as being anticipated by US 6614091 to Downey et al.

Regarding claims 1, Downey discloses an integrated circuit (IC) device in fig. 2 comprising: a semiconductor substrate 26, col. 2 line 54, a metallization interconnect system 28-32, col. 3 line 40, overlying the semiconductor substrate 26, the metallization

interconnect system including multiple first interconnect structure 28 located within a dielectric layer, col. 3 line 41, a bond pad level 53/18 comprising a contact pad (interface between 53 and 28 where 51 and 52 are located), fig. 2, overlying the metallization interconnect system, fig. 2, the contact pad configured for connection external to the device, col. 4 line 8, and a second interconnect structure 53, col. 3 line 30, connected to the contact pad, fig. 2, wherein a portion of the second interconnect structure is disposed in the bond pad level, the second interconnect structure 53 being in physical contact with the multiple first interconnect structures 28 located within the dielectric layer, fig. 2.

Regarding claims 2-3, and 13-14, Downey discloses the IC device wherein a material of the metallization interconnect system comprises copper, col. 3 line 52, wherein a material of the contact pad comprises aluminum, column 3 line 30.

Regarding claim 4, Downey discloses the IC wherein the contact pad is configured for connection external to the device by a bond wire attached, col. 3 line 64.

Regarding claim 6, Downey discloses the IC device wherein a material of the metallization interconnect system comprises copper, col. 3 line 52 and contact pad comprises aluminum, col. 3 line 30, further comprising a barrier material between the copper and the aluminum in the region where the second interconnect structure 53 is in physical contact with the multiple first interconnect structures 28 (or 51/52) located within the dielectric layer, fig. 2 col. 3 lines 19-25.

Regarding claim 8-9,15-16, Downey discloses the IC device wherein the metallization interconnect system further comprises substantially horizontal conductive

copper runners 30, fig. 2, and substantially vertical conductive vias interconnecting overlying and underlying copper, col.3 line 52.

Regarding claim 10, Downey discloses the IC further comprising a passivation layer 18, column 2 line 54, disposed between the second interconnect structure 53 and the dielectric layer, fig 2.

Regarding claim 12, Downey discloses an integrated circuit (IC) device comprising: a metallization interconnect system, fig. 2, located over a substrate 26, the metallization system including multiple first interconnect structure 28 with a dielectric layer, col. 3 line 41, a plurality of contact pads (interface between 53 and 28 where 51 and 52 are located) disposed over the metallization interconnect system, one or more of the plurality of contact pads configured for connection external to the device, col. 4 line 8, line 33, and a second interconnect structure 53 coplanar with at least one of the plurality of contact pads and electrically connected thereto, the second interconnect structure 53 comprising a plurality of conductive elements physically contacting the multiple first interconnect structure 28, fig. 2.

Regarding claim 26, Downey discloses the IC wherein at least a portion of the second interconnects structure 53 is disposed above the contact pad, fig. 2.

Claim Rejections - 35 USC § 103

4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the

Art Unit: 2814

invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

5. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

6. Claims 5, and 27-28 are rejected under 35 U.S.C. 103(a) as being unpatentable over US 6614091 to Downey et al. in view of US 6979896 to Seshan.

Regarding claims 5 and 27-28, Downey does not disclose the IC device wherein contact pad is configured for connection external to the device by a solder bump attached thereto, and wherein the second interconnect structure is a power bus.

However, Seshan discloses the IC device in fig. 5 wherein contact pad 208, col. 4 line 25, is configured for connection external to the device by a solder bump 22, col. 4 line 17, attached thereto. At the time the invention was made; it would have been obvious to one of ordinary skill in the art to use the solder bump teaching of Seshan with Downey, because it would have provided for communicating power and signal to and from circuitry of the IC as taught by Seshan, col. 2 lines 1-2.

With respect to "power bus", the either the metal pad 208 of Seshan or metal pad 53 of Downey obviously can be a power bus that can carry power or signal.

7. Claim 11 is rejected under 35 U.S.C. 103(a) as being unpatentable over US 6614091 to Downey et al. in view of Applicant Admitted Prior Art (AAPA)

Regarding claim 11, Downey does not disclose the IC further comprising a passivation layer overlying the bond pad level.

However, AAPA discloses a IC comprises a passivation layer 158 [0032] overlying the bond pad level. At the time the invention was made; it would have been obvious to one of ordinary skill in the art to use the passivation teaching of AAPA with Downey's device, because the passivation layer would have provided the protection to the aluminum layer and or for further making interconnecting layer.

Conclusion

8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thao X. Le whose telephone number is (571) 272-1708. The examiner can normally be reached on M-F from 8:00 AM - 4:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael M. Fahmy can be reached on (571) 272 -1705. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Art Unit: 2814

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

05 Oct. 2006



THAO X. LE
PRIMARY PATENT EXAMINER